**IGBT Modules** 

#### Power Module (V series) 1200V / 200A / 2-in-1 package

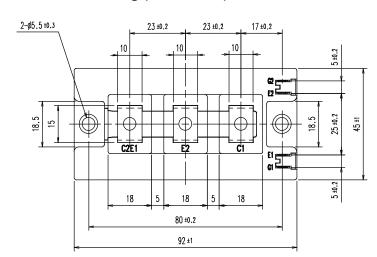
#### **■** Features

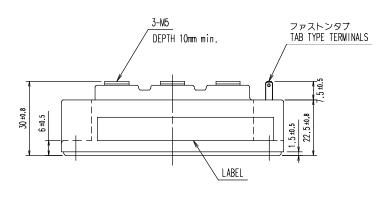
AC-switch
High speed switching
Voltage drive
Low Inductance module structure

#### ■ Applications

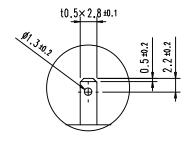
AC-switch for UPS,PCS and etc.

#### ■ Outline drawing (Unit:mm)





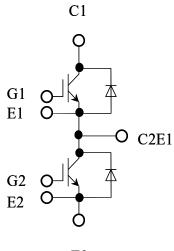




DETAIL TAB TYPE TERMINALS

Weight: 240g (typ.)

#### **■** Equivalent circuit



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#### ■ Absolute maximum ratings (at T<sub>C</sub>= 25°C unless otherwise specified)

Items		Symbols	Conditions		Maximum ratings	Units	
Collector-Emitter voltage		V <sub>CES</sub>			1200	V	
Gate-Emitte	r voltage	$V_{GES}$			±20	V	
-		I <sub>C</sub>	Continuous	T <sub>C</sub> =100°C	200		
Collector cu	rrant	I <sub>C</sub> pulse	1ms		400	Α	
Collector cu	Helit	-1 <sub>C</sub>			200	_ A	
		-I <sub>C</sub> pulse	1ms		400		
Collector power dissipation		Pc	1 device		1500	W	
Junction temperature		$T_{i}$			175		
Operating junction temperature		τ			150		
(under switching conditions)		$T_{jop}$			150	°C	
Case temperature		T <sub>c</sub>			125		
Storage tem	perature	$T_{\rm stg}$			-40 ~ 125		
Isolation	Between terminal and copper base	•	A C . 1 i		2500	\/AC	
voltage	(*1)	$V_{iso}$	AC: 1min.		2500	VAC	
Screw	Mounting	-	M5		2.5~3.5	NI ma	
torque	Terminals	-	M5		2.5~3.5	N m	

<sup>(\*1)</sup> All terminals should be connected together during the test.

**IGBT Modules** 

#### ■ Electrical characteristics (at $T_j$ = 25°C unless otherwise specified)

#### NOTICE:

The external gate resistance ( $R_{\rm g}$ ) shown below is one of our recommend value for the purpose of minimum switching loss. However the optimum  $R_{\rm g}$  depends on circuit configuration and/or environment. We recommend that the  $R_{\rm g}$  has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

Items	Symbols	Condition	ne	Ch	aracterist	ics	Units	
items	Syllibols	Conditio	1115	min.	typ.	max.	UIIIIS	
Zero gate voltage collector current	I <sub>CES</sub>	V <sub>GE</sub> =0V,V <sub>CE</sub> =1200V		-	ı	2.0	mA	
Gate-Emitter leakage current	I <sub>GES</sub>	V <sub>CE</sub> =0V,V <sub>GE</sub> =±20V		-	-	400	nA	
Gate-Emitter threshold voltage	$V_{GE(th)}$	V <sub>CE</sub> =20V,I <sub>C</sub> =200mA	V <sub>CE</sub> =20V,I <sub>C</sub> =200mA		6.5	7.0	V	
	V <sub>CE(sat)</sub>		T <sub>j</sub> =25°C	-	1.95	2.40		
	(terminal)	$V_{GE}$ =15V, $I_{C}$ =200A	T <sub>j</sub> =125°C	-	2.25	-		
Collector-Emitter	(terrilliai)		T <sub>j</sub> =150°C	-	2.30	-	V	
saturation voltage	V		T <sub>j</sub> =25°C	-	1.75	2.20	7 V	
	V <sub>CE(sat)</sub>		2.05	-				
	(chip)		T <sub>i</sub> =150°C	-	2.10	-		
Internal gate resistance	R <sub>g(int)</sub>	-		-	3.8	-	Ω	
Input capacitance	C ies	V <sub>CE</sub> =10V, V <sub>GE</sub> =0V, J	$V_{CE}$ =10V, $V_{GE}$ =0V, $f$ =1MHz		18.2	-	nF	
	t on			-	600	-		
Turn-on time	t <sub>r</sub>	$V_{\rm CC}$ =600V, $I_{\rm C}$ =200A, $V_{\rm GE}$ =±15V,		-	200	-	nsec	
	t <sub>r(i)</sub>			-	50	-		
Turn-off time	t off	$R_g = 2.7\Omega, T_j = 150^{\circ}\text{C}, L_s = 30\text{nH}$			-	1		
rum-on ume	t <sub>f</sub>	1		-	80	-	1	
	W		T <sub>i</sub> =25°C	-	1.85	2.30		
	V <sub>F</sub>	$V_{GE} = 0V, I_{F} = 200A$	T <sub>i</sub> =125°C	-	2.00	-		
Command on voltage	(terminal)		T <sub>i</sub> =150°C	-	1.95	-	\/	
Forward on voltage	V <sub>F</sub> V	V <sub>GE</sub> =0V,I <sub>F</sub> =200A	T <sub>i</sub> =25°C	-	1.70	2.15	V	
			T <sub>i</sub> =125°C	-	1.85	-		
	(chip)		T <sub>j</sub> =150°C	-	1.80	-		
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> =200A		-	150	-	nsec	

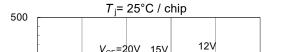
#### **■** Thermal resistance characteristics

Items	Cymbolo	Conditions	Characteristics			Units
items	Symbols	Conditions		typ.	max.	UIIIIS
Thermal resistance	D	IGBT	-	-	0.100	
(1device)	R <sub>th(j-c)</sub>	FWD	-	-	0.160	°C/W
Contact thermal resistance	D	with thermal compound		0.025		C/VV
(1device) (*1)	R <sub>th(c-f)</sub>	with thermal compound	-	0.025	<u>-</u> 	

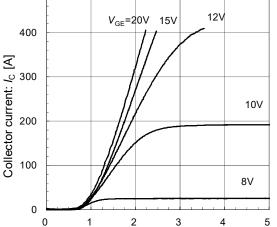
<sup>(\*1)</sup> This is the value which is defined mounting on the additional cooling fin with thermal compound.



**IGBT Modules** 

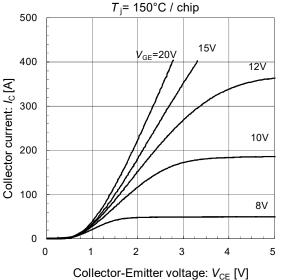


Collector current vs. Collector-Emitter voltage (typ.)

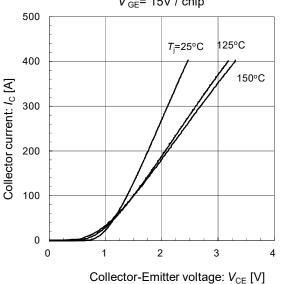


Collector-Emitter voltage: V<sub>CE</sub> [V]

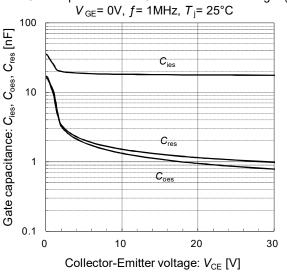
Collector current vs. Collector-Emitter voltage (typ.)



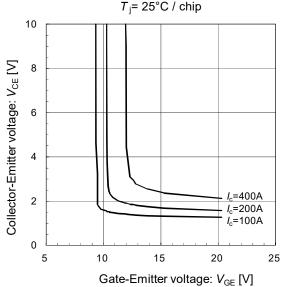
Collector current vs. Collector-Emitter voltage (typ.)  $V_{\rm GE}$ = 15V / chip



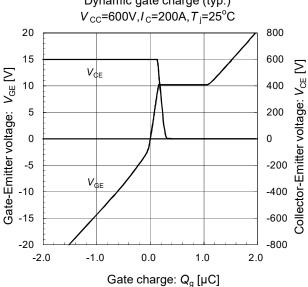
Gate capacitance vs. Collector-Emitter voltage (typ.)



Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)

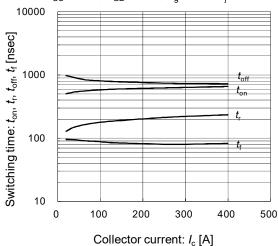


Dynamic gate charge (typ.)

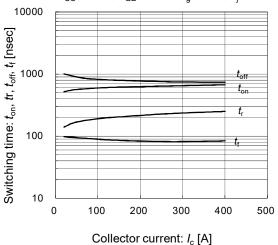


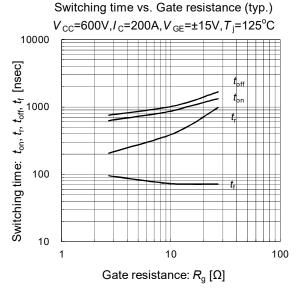
**IGBT Modules** 

Switching time vs. Collector current (typ.)  $V_{CC}$ =600V,  $V_{GE}$ =±15V,  $R_g$ =2.7 $\Omega$ ,  $T_i$ =125°C

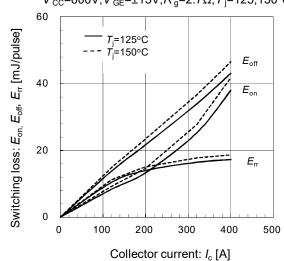


Switching time vs. Collector current (typ.)  $V_{\text{CC}}$ =600V, $V_{\text{GE}}$ =±15V, $R_{\text{g}}$ =2.7 $\Omega$ , $T_{\text{i}}$ =150°C

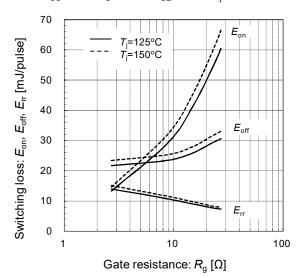




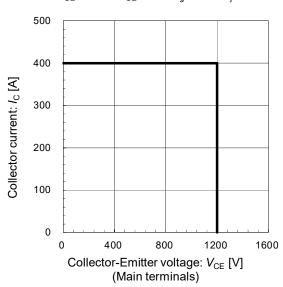
Switching loss vs. Collector current (typ.)  $V_{CC}$ =600V,  $V_{GE}$ =±15V,  $R_{g}$ =2.7 $\Omega$ ,  $T_{i}$ =125,150°C



Switching loss vs. Gate resistance (typ.)  $V_{\rm CC}$ =600V, $I_{\rm C}$ =200A, $V_{\rm GE}$ =±15V, $T_{\rm i}$ =125,150°C

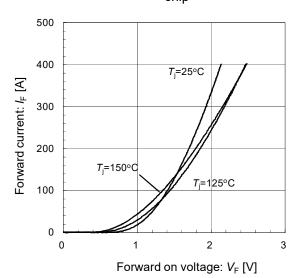


Reverse bias safe operating area (max.) + $V_{GE}$ =15V, - $V_{GE}$ =15V, $R_{g}$ =2.7 $\Omega$ , $T_{j}$ =150°C

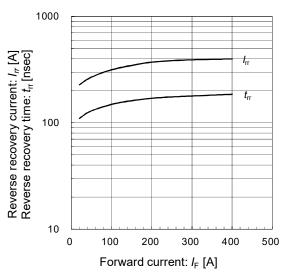


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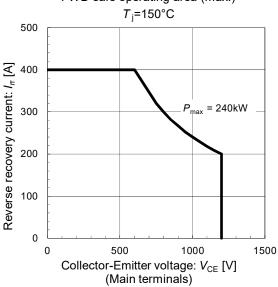
Forward current vs. Forward voltage (typ.) chip



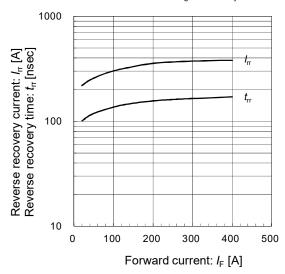
Reverse recovery characteristics (typ.)  $V_{CC}$ =600V,  $V_{GE}$ =±15V,  $R_g$ =2.7 $\Omega$ ,  $T_i$ =150°C



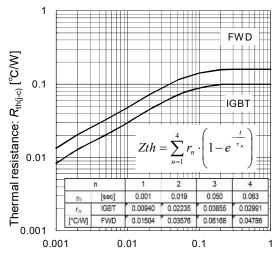
FWD safe operating area (max.)



Reverse recovery characteristics (typ.)  $V_{CC}$ =600V,  $V_{GE}$ =±15V,  $R_q$ =2.7 $\Omega$ ,  $T_i$ =125°C



Transient thermal resistance (max.)



Pulse width :  $P_w$  [sec]



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